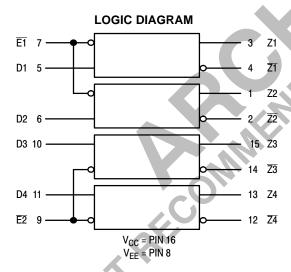
Quad Bus Driver

The MC10192 contains four line drivers with complementary outputs. Each driver has a Data (D) input and shares an $\overline{E}nable$ (\overline{E}) input with another driver. The two driver outputs are the uncommitted collectors of a pair of NPN transistors operating as a current switch. Each driver accepts 10K MECL input signals and provides a nominal signal swing of 800 mV across a 50 Ω load at each output collector. Outputs can drive higher values of load resistance, provided that the combination of I_R drop and load return voltage V_{LR} does not cause an output collector to go more negative than –2.4 V with respect to V_{CC} . To avoid output transistor breakdown, the load return voltage should not be more positive than +5.5 V with respect to V_{CC} . When the \overline{E} input is high, both output transistors of a driver are nonconducting. When not used, the \overline{E} inputs, as well as the D inputs, may be left open.

- Open Collector Outputs Drive Terminated Lines or Transformers
- 50 kW Input Pulldown Resistors on All Inputs (Unused Inputs May Be Left Open)
- Power Dissipation = 575 mW typ/pkg (No Load)
- Propagation Delay = 3.5 ns typ (\overline{E} Output) 3.0 ns typ (D — Output)



TRUTH TABLE

Inp	uts	Output					
Ē	D	Z	Z				
Н	Х	Н	Н				
L	Н	Н	L				
L	L	L	Н				

Note: Unused outputs must be terminated to V_{CC} for proper operation.



ON Semiconductor

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CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



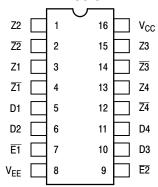
A = Assembly Location

WL = Wafer Lot

YY = Year

WW = Work Week

DIP PIN ASSIGNMENT



Pin assignment is for Dual-in-Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

ORDERING INFORMATION

Device	Package	Shipping
MC10192L	CDIP-16	25 Units / Rail
MC10192P	PDIP-16	25 Units / Rail
MC10192FN	PLCC-20	46 Units / Rail

ELECTRICAL CHARACTERISTICS

						Test I	_imits			
			Pin Under	-3	0°C	+2	5°C	+85	5°C	
Characteris	stic	Symbol	Test	Min	Max	Min	Max	Min	Max	Unit
Power Supply Drain Cu	rrent	Ι _Ε	8		154		140		154	mAdc
Input Current		I _{inH}	5		350		220		220	μAdc
		I _{inL}	5	0.5		0.5		0.3		μAdc
Output Current High	Logic 1	I _{OH}	2				2.0			mAdc
Output Current Low	Logic 0	I _{OL}	2	13.5	18.0	14.0	18.0	14.0	19.0	mAdc
Threshold Current High	Logic 1	I _{OHC}	2		2.0		2.0		2.0	mAdc
Threshold Current Low	Logic 0	I _{OLC}	2	13.5		14.0		14.0		mAdc
Output Sink Current Lov	w Logic 0	I _{OS}	2	13.3		13.9		13.3		mAdc
Load Return Voltage Ab Rating (Note 1.)	osolute Max	V_{LR}			5.5		5.5		5.5	٧
Output Voltage Low (No	ote 2.)	V _{OLS}				-2.4				V
Switching Times	(50 Ω Load)									ns
Propagation Delay	E to Output D to Output	t _{PHL} t _{PLH}				2.0 1.5	6.0 4.5			
Rise/Fall Time	(20 to 80%)	t _{TLH} t _{THL}					3.3			

^{1.} The 5.5V value is a maximum rating, do not exceed. A 270Ω resistor will prevent output transistor breakdown.

ELECTRICAL CHARACTERISTICS (continued)

				TEST VOL	TAGE VALU	IES (Volts)		
	@ Test Te	mperature	V _{IHmax}	$V_{\rm ILmin}$	V _{IHAmin}	V _{ILAmax}	V _{EE}	
		−30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
		+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
		+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
		Pin	TEST \	OLTAGE API	PLIED TO PI	NS LISTED E	BELOW	04)
Characteristic	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	(V _{CC}) Gnd
Power Supply Drain Current	ΙΕ	8					8	16
Input Current	I _{inH}	5	5				8	16
	l _{inL}	5		5			8	16
Output Current High Logic 1	Гон	2		5,6,10,11			8	16
Output Current Low Logic 0	l _{OL}	2	5,6,10,11				8	16
Threshold Current High Logic 1	I _{OHC}	2		5,7,9,10,11		6	8	16
Threshold Current Low Logic 0	I _{OLC}		5,10,11	7,9	6		8	16
Output Sink Current Low Logic 0	Ios	2	5,6,10,11				8	16
Load Return Voltage Absolute Max Rating (Note 1.)	V_{LR}						8	16
Output Voltage Low (Note 2.)	V _{OLS}						8	16

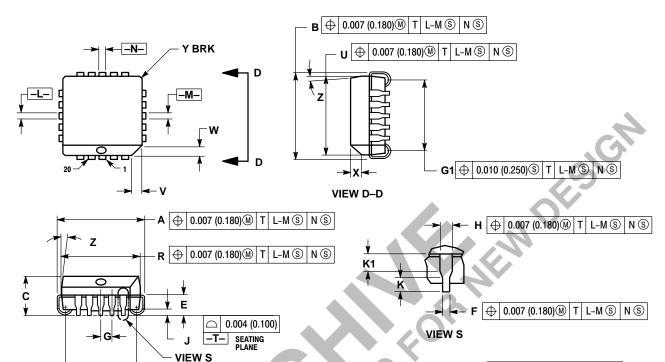
Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

^{2.} Limitations of load resistor and load return voltage combinations. Refer to page 1 description.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF MICE. NOT PRESCO

- IOTES:

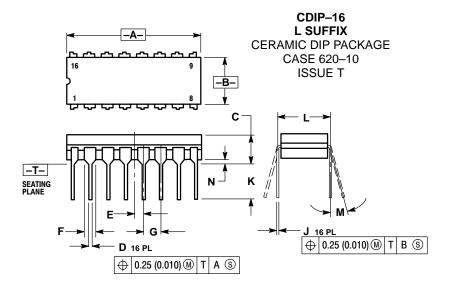
 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2 °	10°
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	



NOTES:

- ANIES.

 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

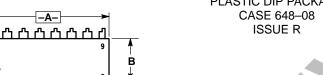
 CONTROLLING DIMENSION: INCH.

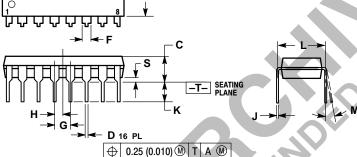
 DIMENSION L TO CENTER OF LEAD WHEN

- FORMED PARALLEL.
 DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
E	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300 BSC		7.62	BSC 4	
M	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE





- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIM	ETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

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